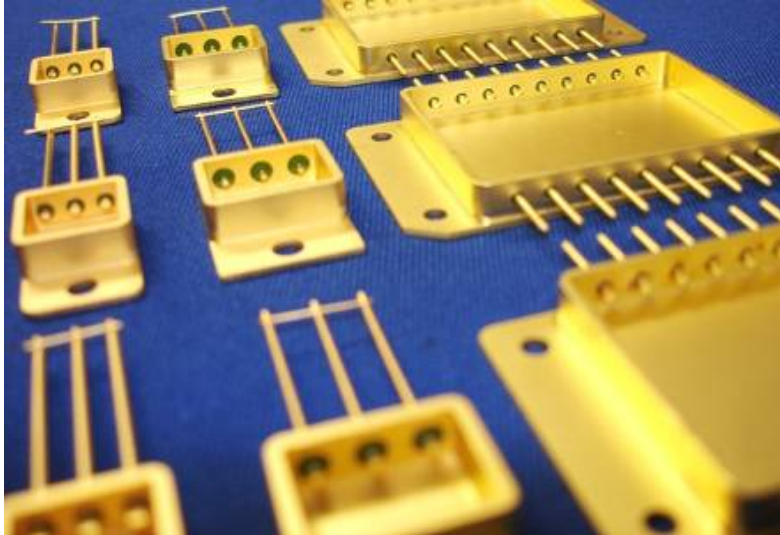




CPS Technologies Offers TO-250 Series Type Packages
Ideal for military, electronics, satellite, and aerospace markets



CPS Technologies, the worldwide leader in the design and production of metal matrix composites, now offers TO-250 type products, which can be manufactured in a variety of combinations. A cold rolled steel frame with hermetic seals made with Alloy #52 or Copper Cored Alloy #52 pins in a compression glass seal or ceramic terminal. Bottom choices can be OFHC Copper, Copper Moly, Copper Tungsten or Glidcop. Braze material is 72% Ag / 28% Cu (BT braze). CPS' highly engineered hermetic microelectronic packages enable successful communication for military, electronics, satellite, and aerospace markets.

With over sixty years of combined experience in hermetic microelectronic packaging, CPS has supplied and assembled AlSiC (aluminum silicon carbide) components for use in hermetic microelectronic packages for select customers since 1987. It is now pleased to offer hermetic microelectronic packages to the market at large.

CPS operates in a vertically integrated 38,000 square foot manufacturing facility in Norton, MA, which is certified to ISO:9001:2000. Providing quality assurance testing to MID-STD 883 and MIL-STD 202, CPS is compliant to DFARS clause 252.225-7014 ALT.1.

CPS' plating capabilities include Electrolytic Nickel per QQ-N-290 and ASTM B-689, Electroless Nickel per Mil-C-26074E and ASTM B-733, and Gold per ASTM B-488 and Mil-G-45205C.

CPS' test capabilities, Air to Air temperature cycle/shock per MIL-STD-883, method 1010, Steam age/solderability testing per MIL-STD-883, method 2003, Lead Fatigue per MIL-STD-883, method 2004, Hermeticity validation to 1 x 10⁻¹⁰ cc/sec of helium per MIL-STD-883, method 1014, Insulation resistance to 10 giga ohms at 500 VDC per MIL-STD-883, method 1003, Salt spray per MIL-STD-883, method 1009, Compliance to JEDEC Std. 9 and Mil-STD-883

About CPS Technologies Corporation

CPS Technologies Corporation is the worldwide leader in the design and high-volume production of metal matrix composites. With over 30 years combined experience, CPS engineers and scientists use a net-shape fabrication process, including patented QuickSet™ injection molding and QuickCast™ infiltration. AlSiC components are utilized in applications in the wireless communications infrastructure, high-performance microprocessor, motor controller, and other microelectronic markets. CPS' customers include TI, Motorola, HP, Raytheon, Northrop, Solitron, Agilent and Amkor. For more information on CPS' AlSiC components, contact CPS at 1 (508) 222-0614 x 242; e-mail marko@alsic.com, or Cheryl Oliveira at x 247; e-mail coliveira@alsic.com or visit www.alsic.com.